TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

# 2SK3562

## **Switching Regulator Applications**

• Low drain-source ON resistance: RDS (ON) =  $0.9\,\Omega$  (typ.)

• High forward transfer admittance:  $|Y_{fs}| = 5.0S$  (typ.)

• Low leakage current: IDSS = 100  $\,\mu$  A (VDS = 600 V)

• Enhancement mode:  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

# **Maximum Ratings (Ta = 25°C)**

| Characteristics                                      |                              | Symbol           | Rating  | Unit |  |
|--|------------------------------|------------------|---------|------|--|
| Drain-source voltage                                 |                              | $V_{DSS}$        | 600     | V    |  |
| Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ ) |                              | V <sub>DGR</sub> | 600     | V    |  |
| Gate-source voltage                                  |                              | V <sub>GSS</sub> | ±30     | V    |  |
|  | DC (Note 1)                  | ID               | 6       | А    |  |
| Drain current  | Pulse (t = 1 ms)<br>(Note 1) | I <sub>DP</sub>  | 24      |      |  |
| Drain power dissipation (Tc = 25°C)                  |                              | P <sub>D</sub>   | 40      | W    |  |
| Single pulse avalanche energy (Note 2)               |                              | E <sub>AS</sub>  | 345     | mJ   |  |
| Avalanche current                                    |                              | I <sub>AR</sub>  | 6       | Α    |  |
| Repetitive avalanche energy (Note 3)                 |                              | E <sub>AR</sub>  | 4       | mJ   |  |
| Channel temperature                                  |                              | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature range                            |                              | T <sub>stg</sub> | -55~150 | °C   |  |

# Unit: mm \$\delta\_{3.2\pmu 0.2} \quad \text{10\pmu 0.3} \quad \text{2.7\pmu 0.2} \quad \text{2.54} \quad \text{2.55} \quad \text{2.54} \quad \text{2.55} \quad \text{2.54} \quad \text{2.55} \quad \quad \text{2.55} \quad \quad \text{2.55} \quad \quad \text{2.55} \quad \text{2.55} \quad \quad \quad \text{2.55} \quad \qu

Weight: 1.7 g (typ.)

### **Thermal Characteristics**

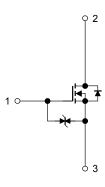
| Characteristics                        | Symbol                 | Max   | Unit |
|--|------------------------|-------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 3.125 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 62.5  | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub> = 90 V, T<sub>Ch</sub> = 25°C(initial), L = 16.8 mH, I<sub>AR</sub> = 6 A, R<sub>G</sub> = 25  $\Omega$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.





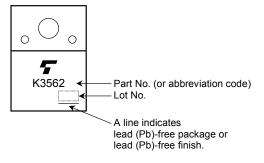
# Electrical Characteristics (Ta = 25°C)

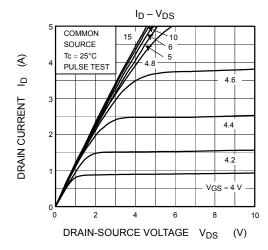
| Chara                        | acteristics    | Symbol               | Test Condition  | Min | Тур. | Max  | Unit |
|------------------------------|----------------|----------------------|---|-----|------|------|------|
| Gate leakage cur             | rrent          | I <sub>GSS</sub>     | $V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$   | _   | _    | ±10  | μΑ   |
| Gate-source brea             | akdown voltage | V (BR) GSS           | $I_G=\pm 10~\mu A,~V_{DS}=0~V$  | ±30 | _    | _    | V    |
| Drain cut-off curr           | ent            | I <sub>DSS</sub>     | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V  | _   | _    | 100  | μА   |
| Drain-source bre             | akdown voltage | V (BR) DSS           | $I_D = 10$ mA, $V_{GS} = 0$ V   | 600 | _    | _    | V    |
| Gate threshold ve            | oltage         | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA   | 2.0 | _    | 4.0  | V    |
| Drain-source ON              | resistance     | R <sub>DS (ON)</sub> | $V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$  | _   | 0.9  | 1.25 | Ω    |
| Forward transfer             | admittance     | Y <sub>fs</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A  | 1.2 | 5.0  | _    | S    |
| Input capacitance            |                | C <sub>iss</sub>     | V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz  | _   | 1050 | _    | pF   |
| Reverse transfer capacitance |                | C <sub>rss</sub>     |   | _   | 10   | _    |      |
| Output capacitance           |                | C <sub>oss</sub>     |   | _   | 110  | _    |      |
| Switching time               | Rise time      | t <sub>r</sub>       | $\begin{array}{c c} 10 \text{ V} \\ \text{VGS} \\ 0 \text{ V} \\ \hline \\ 50  \\ \end{array} \begin{array}{c} \text{I}_{D} = 3 \text{ A} \\ \text{VOUT} \\ \\ \text{$\downarrow$} \\ $ | _   | 20   |      |      |
|                              | Turn-on time   | t <sub>on</sub>      |   | _   | 40   | -    | 20   |
|                              | Fall time      | t <sub>f</sub>       |   |     | 35   |      | ns   |
|                              | Turn-off time  | t <sub>off</sub>     | Duty $\leq$ 1%, $t_W = 10 \mu s$  | _   | 130  |      |      |
| Total gate charge            |                | Qg                   |   | _   | 28   | _    |      |
| Gate-source charge           |                | Q <sub>gs</sub>      | $V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$   | _   | 16   | _    | nC   |
| Gate-drain charge            |                | Q <sub>gd</sub>      |   | _   | 12   | _    |      |

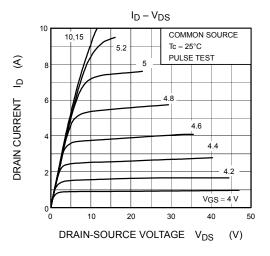
# Source-Drain Ratings and Characteristics (Ta = 25°C)

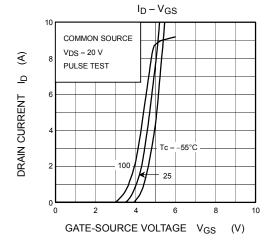
| Characteristics                           | Symbol           | Test Condition                                | Min | Тур. | Max  | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  | _   | _   | _    | 6    | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _   | _   | _    | 24   | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | $I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$  | _   | _    | -1.7 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | $I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V},$ | _   | 1000 | _    | ns   |
| Reverse recovery charge                   | Q <sub>rr</sub>  | dI <sub>DR</sub> /dt = 100 A/μs               | _   | 7.0  | _    | μС   |

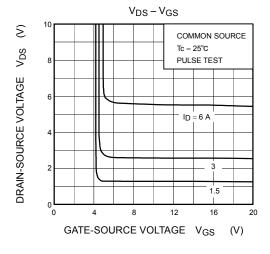
# Marking

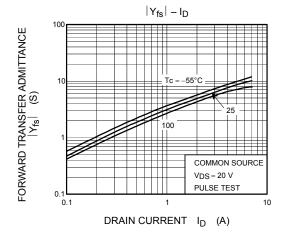


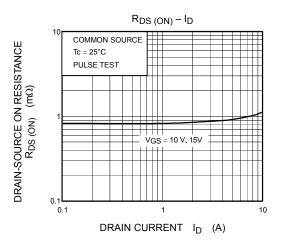


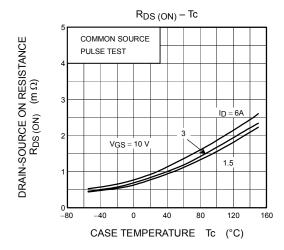


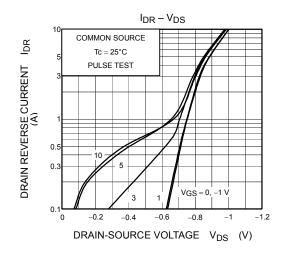


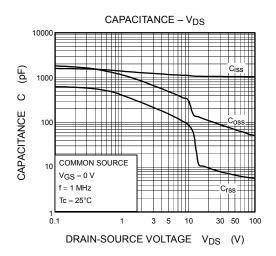


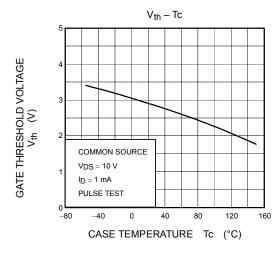


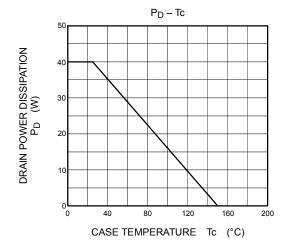


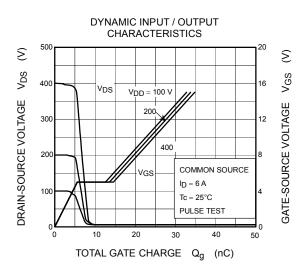


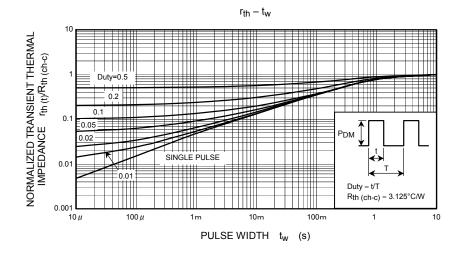


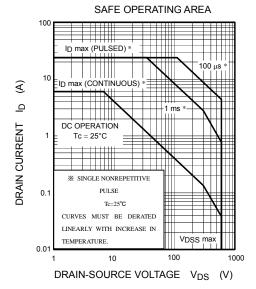


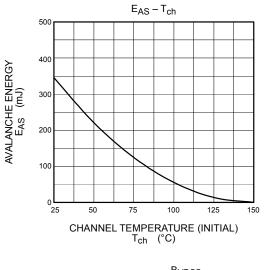


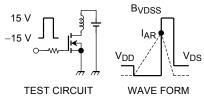












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 16.8 \text{mH} \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot l^2 \cdot \left( \frac{BVDSS}{BVDSS} - V_{DD} \right)$$

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